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TI **Silver-containing tin-base solder**
IN Daigo, Takashi; Watanabe, Osamu
PA Tokuriki Honten Kk, Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF

DT Patent
LA Japanese

FAN.CNT 1

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| PI | JP 06269981 | A2 | 19940927 | JP 1993-58543 | 19930318 |
| PRAI | JP 1993-58543 | | 19930318 | | |
| AB | A solder contains Ag 5-20, Sn 70-90, Cu 0.05-10, and Pd 0.05-2%. The solder has high corrosion resistance and elec. and thermal cond. and is suitable for elec. industry. | | | | |